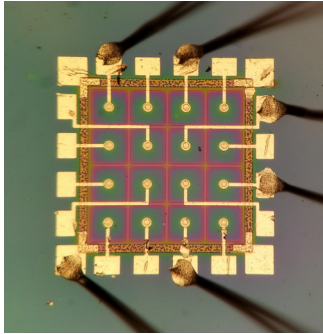


Development of (V)UV-Sensitive GaN Geiger-Mode Photodiodes



Minkyu Cho, Theeradetch Detchprohm, Russell Dupuis, Eliza Gazda, Hoon Jeong, Mi-Hee Ji, Marzieh Noodeh-Bakhtiary, Shyh-Chiang Shen, Zhiyu Xu



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ENERGY

Office of
Science

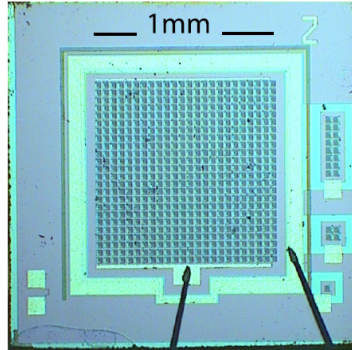
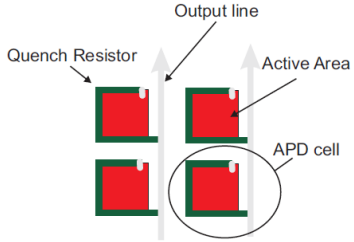
DE-SC0019133

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&
Center for Relativistic Astrophysics

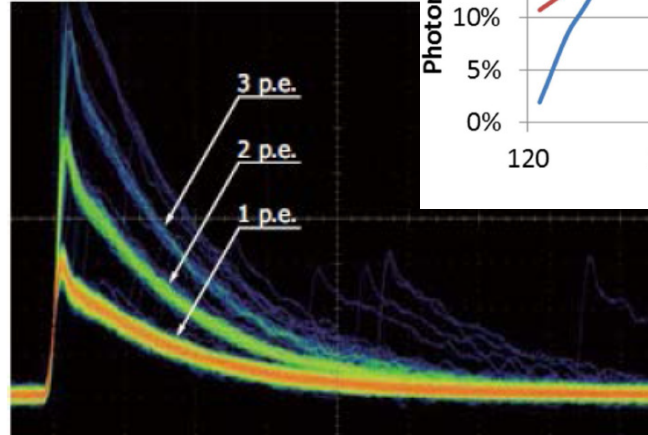


The Silicon Photomultiplier or G-APD



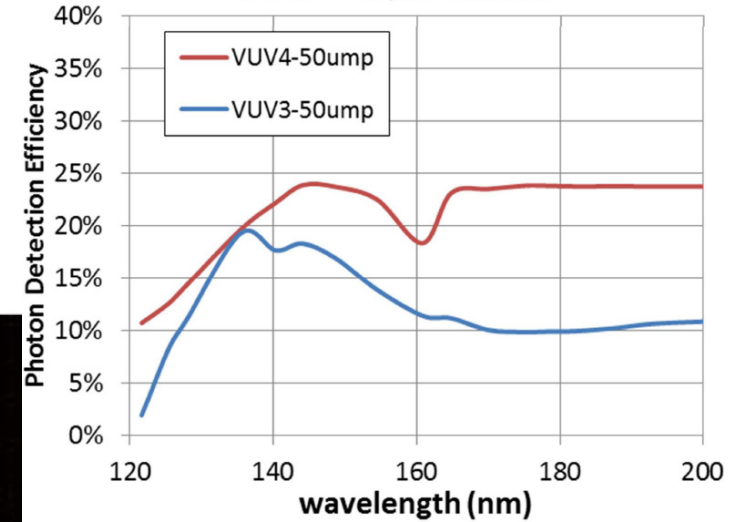
MEPhi/Pulsar SiPM 2004

Pulse height



Time Hamamatsu MPPC techinfo

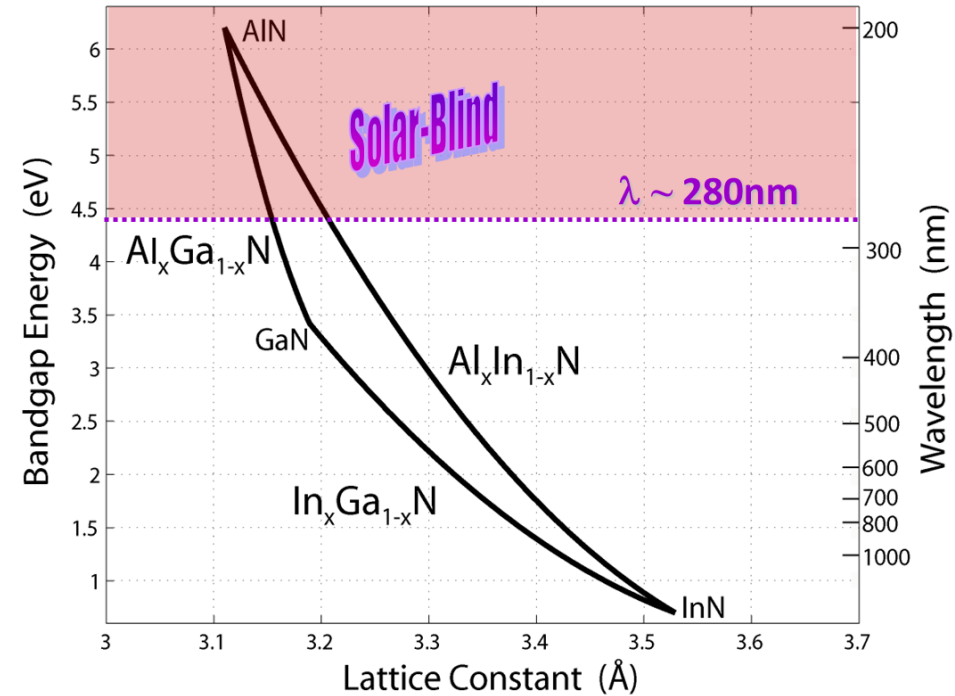
PDE measurement data
Vover = 4V, in vacuum



Can the SiPM concept be transferred to GaN?

Why GaN?

- Large bandgap
 - Tunable bandgap -> tunable spectral response
 - Potential for high UV-VUV sensitivity with little to no red sensitivity
- Sufficiently clean substrates are available
 - Geiger-mode is possible
- Increasing use of GaN in high-power electronics, LEDs, Lasers
 - Increasing supply of GaN-substrates
 - Cleaner substrates
 - Lower cost



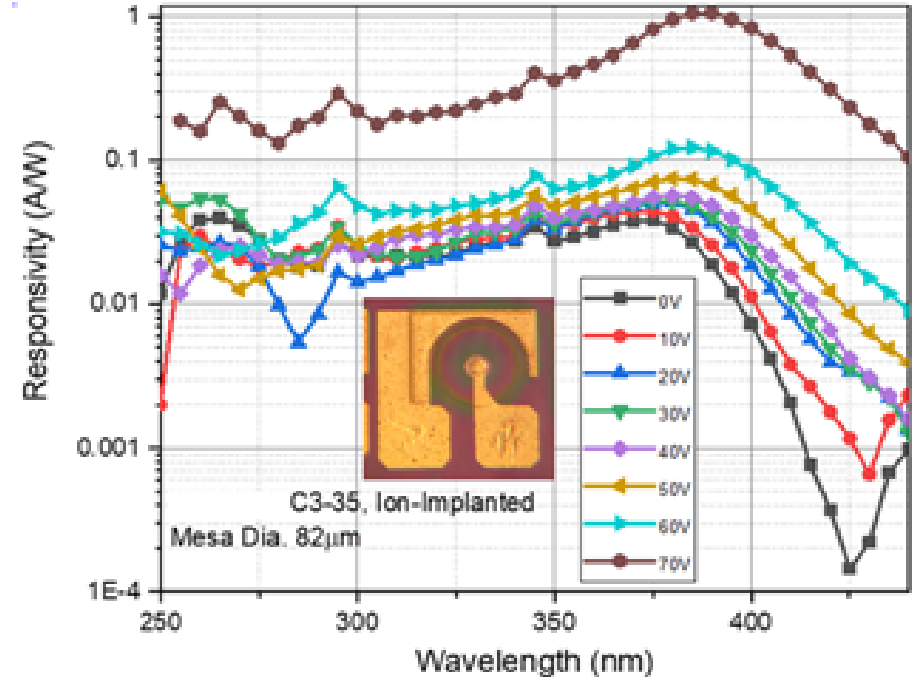
The GaN Technical and Intellectual Challenge

● Geiger-mode in GaN is unexplored

- Breakdown probability?
- Temperature dependencies?
- Electric field dependencies?
- Quenching?

● Device Fabrication

- Uniform breakdown characteristics
- Low dark-count rates
- Scalability
- Arrays
- ...

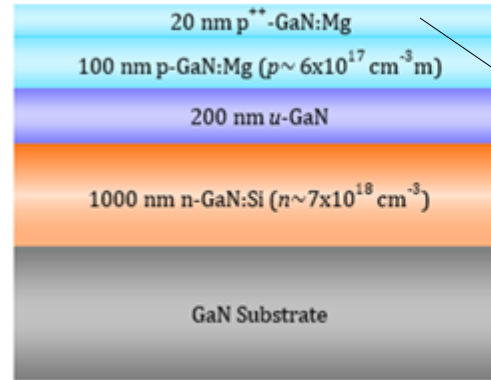


Spectral response of a 82 um-dia. Georgia Tech GaN APD

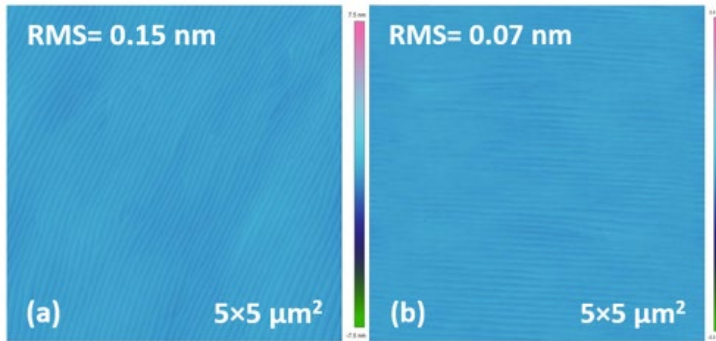
Georgia Tech GaN Structures

<https://doi.org/10.1117/12.2576888>

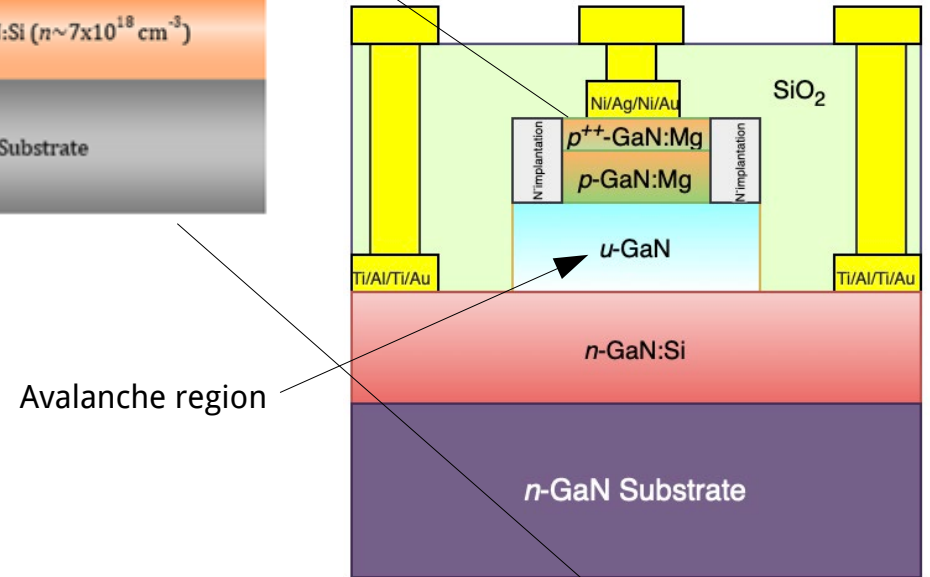
- epitaxial growth



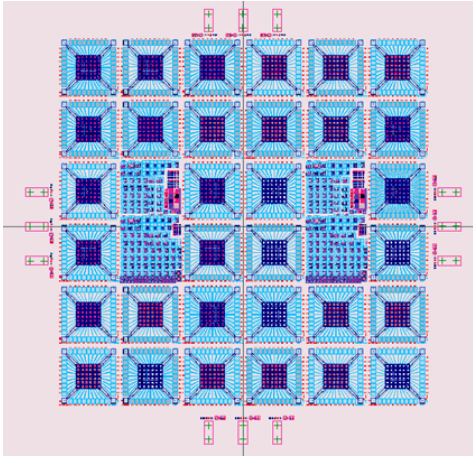
surface roughness:



Growth on: u -GaN/sapphire n-GaN bulk substrate

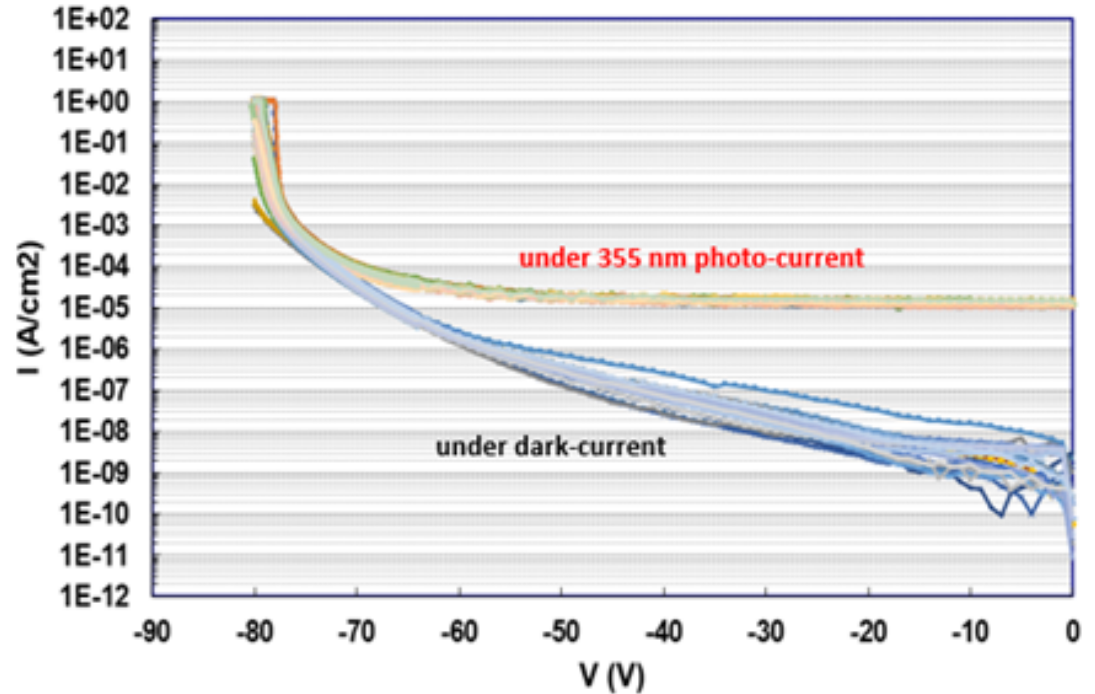


IV-Curves



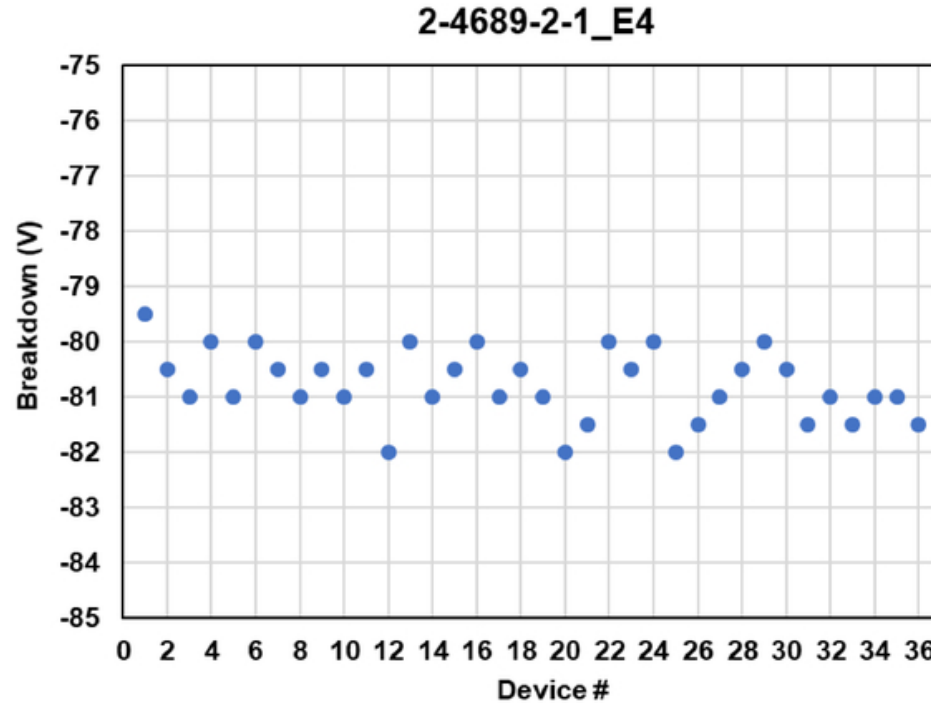
36 diode array of 60 um cells

- Uniform dark current characteristics
- Uniform light response



<https://doi.org/10.1117/12.2576888>

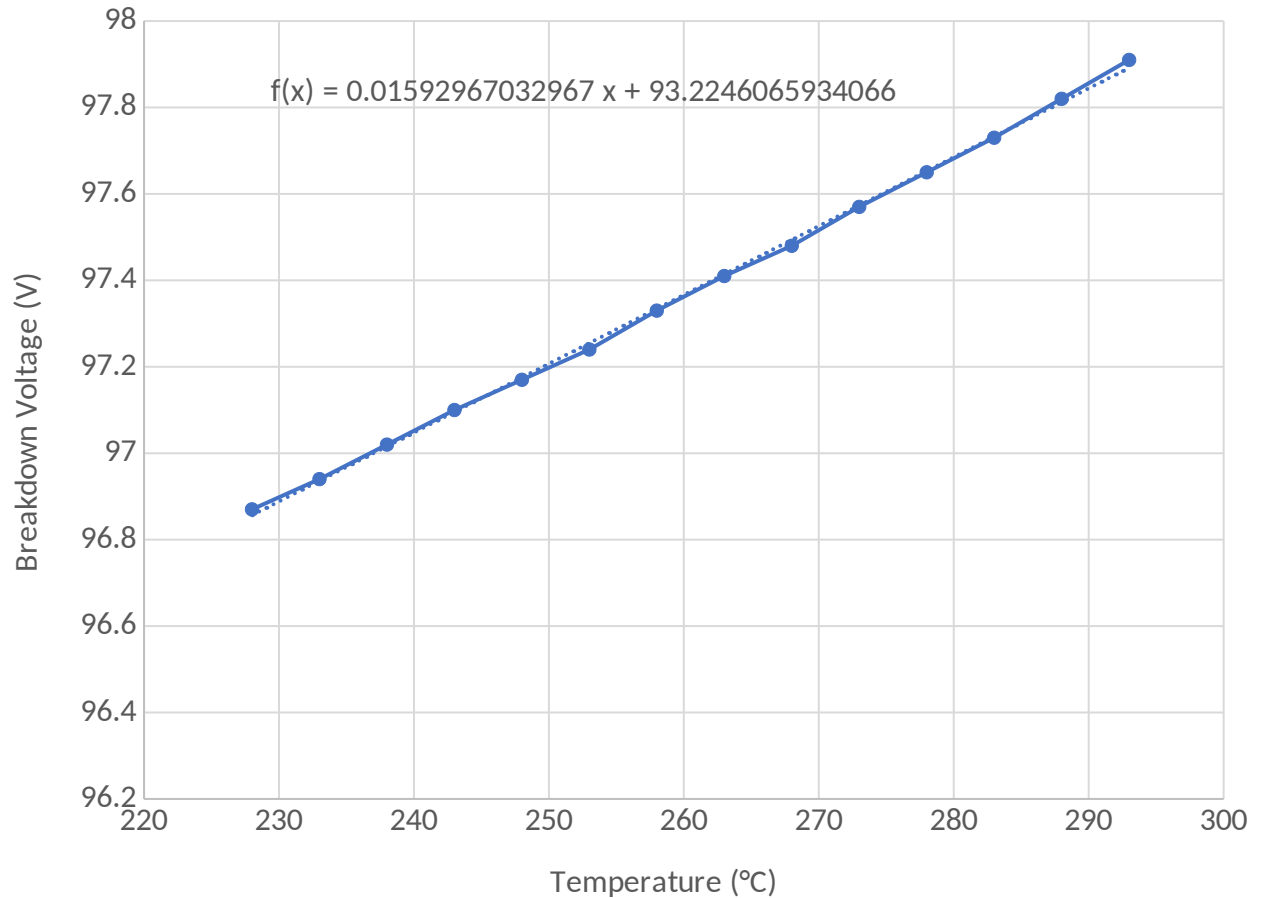
Breakdown Voltage Uniformity



- Uniform breakdown characteristics (<1% variations)

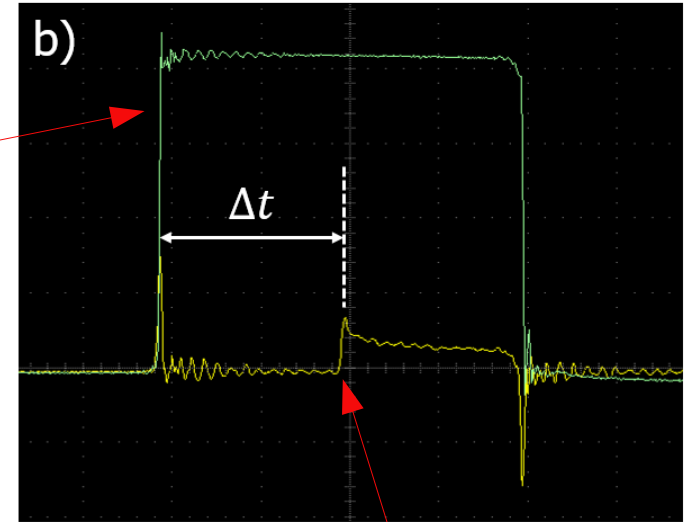
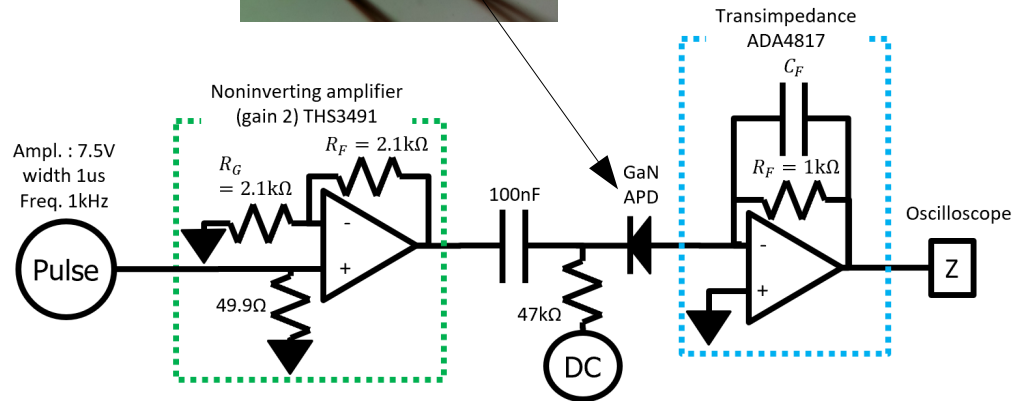
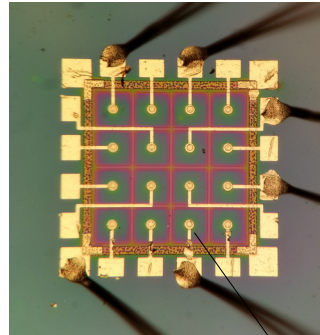
Breakdown Voltage vs. Temperature

- Breakdown voltage shifts 0.02%/K (SiPMs 0.1%/K)

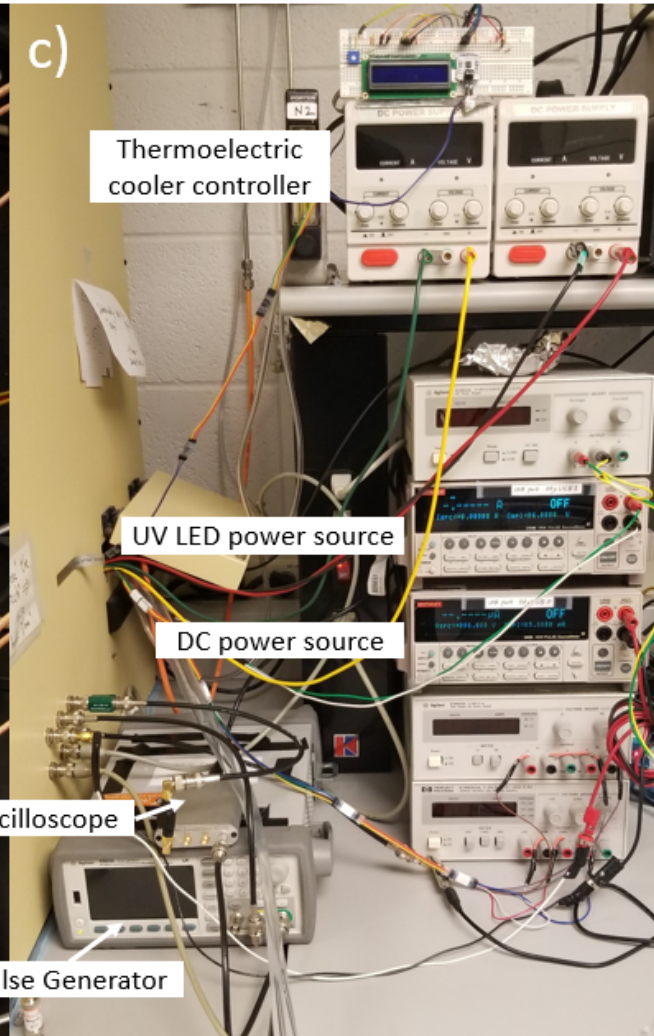
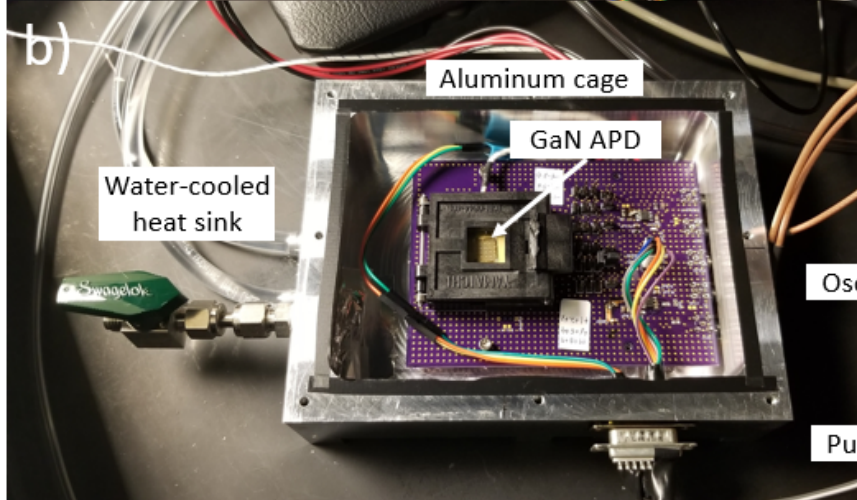
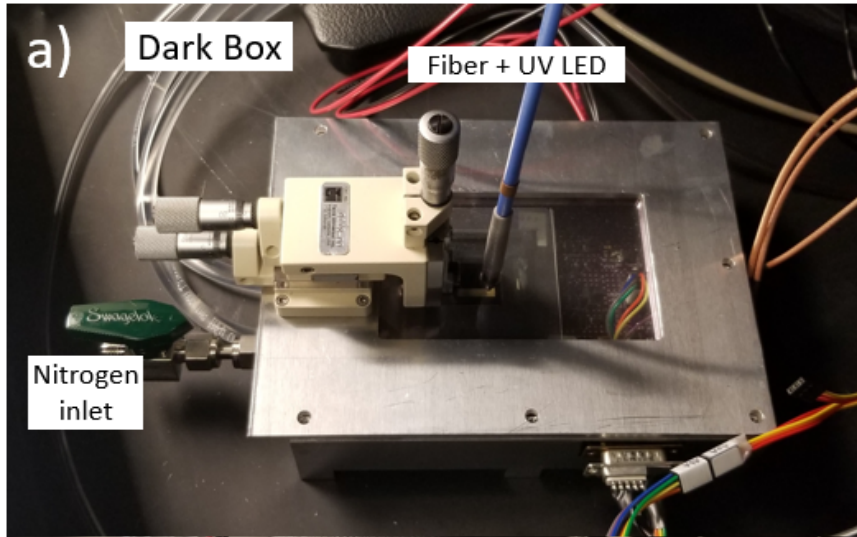


Geiger Mode Measurements

- New territory
-> Develop setups from scratch

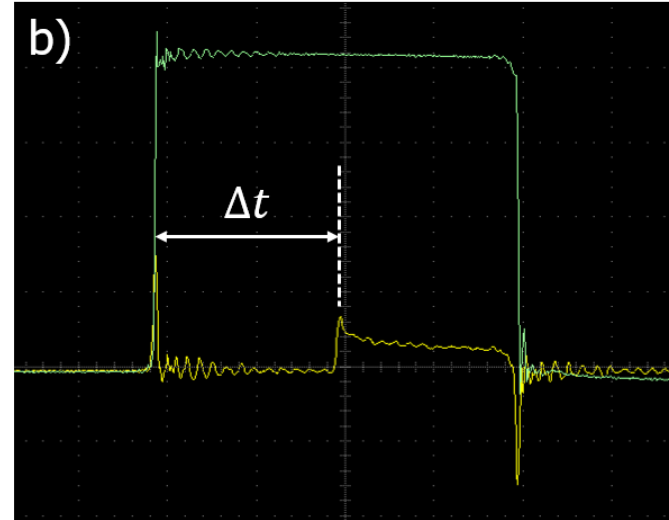
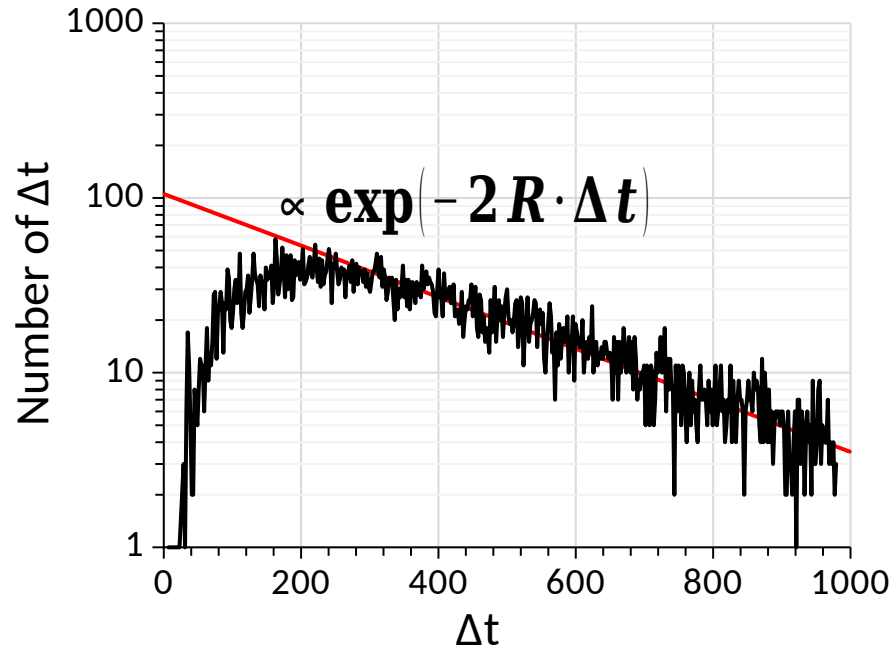


dark-count breakdown



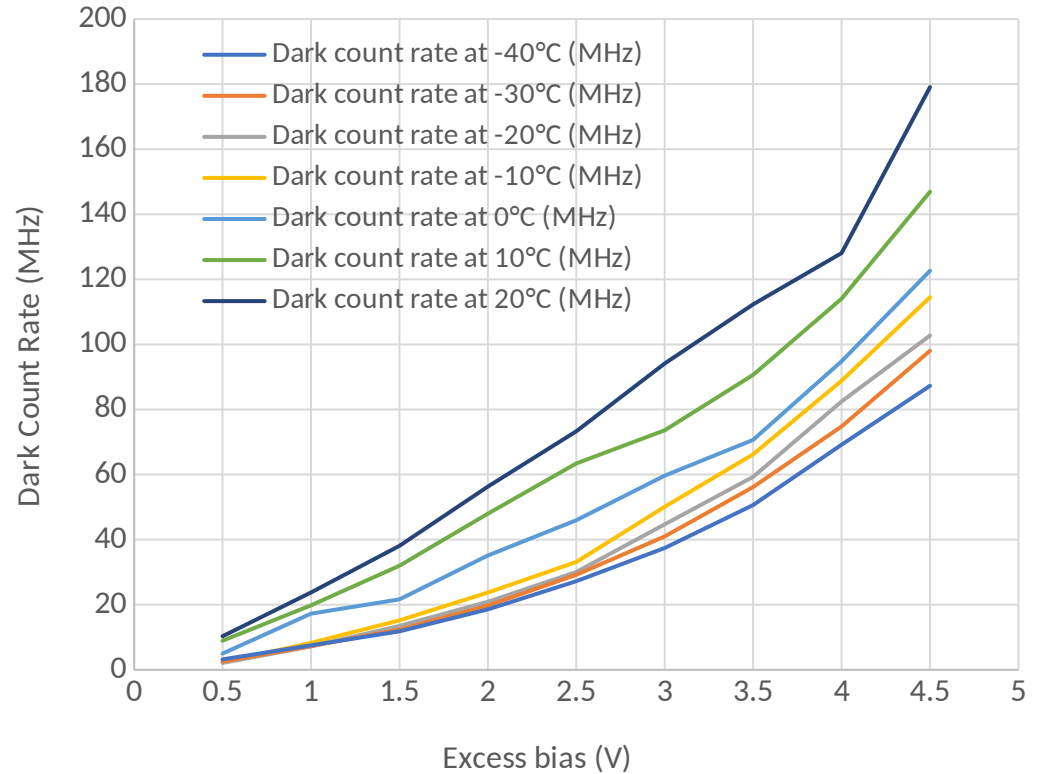
Count Rate Measurements

Determine count rate from Δt distribution



Dark-Count Rates

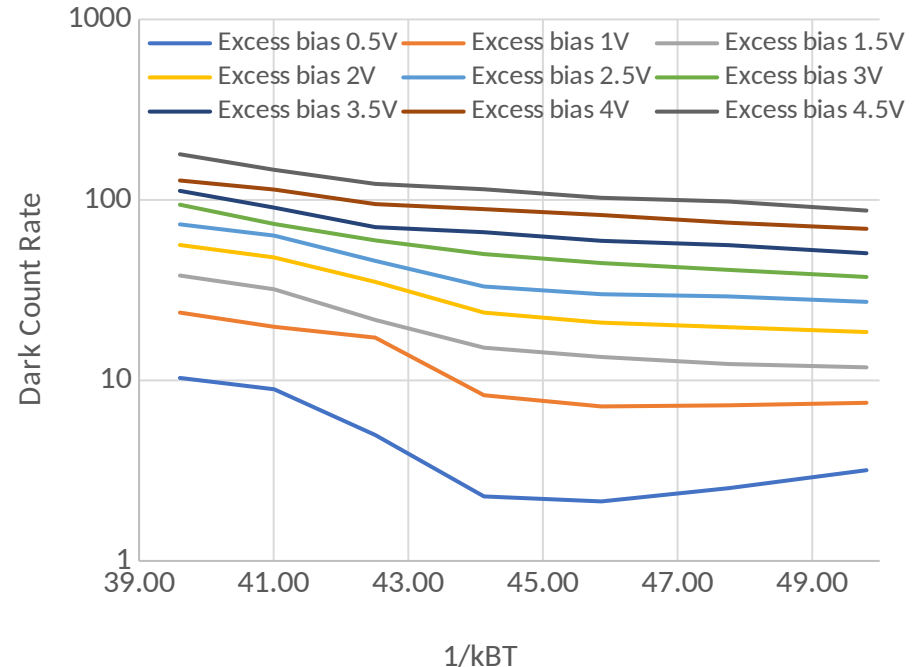
- Temperature range -40°C - 20°C
- Overvoltages 0.5 V - 4 V
- Dark count rates (DCR) > 10 MHz



High dark-count rate prevents operation at higher overvoltages (cf. early SiPMs)

Dark-Count Rates

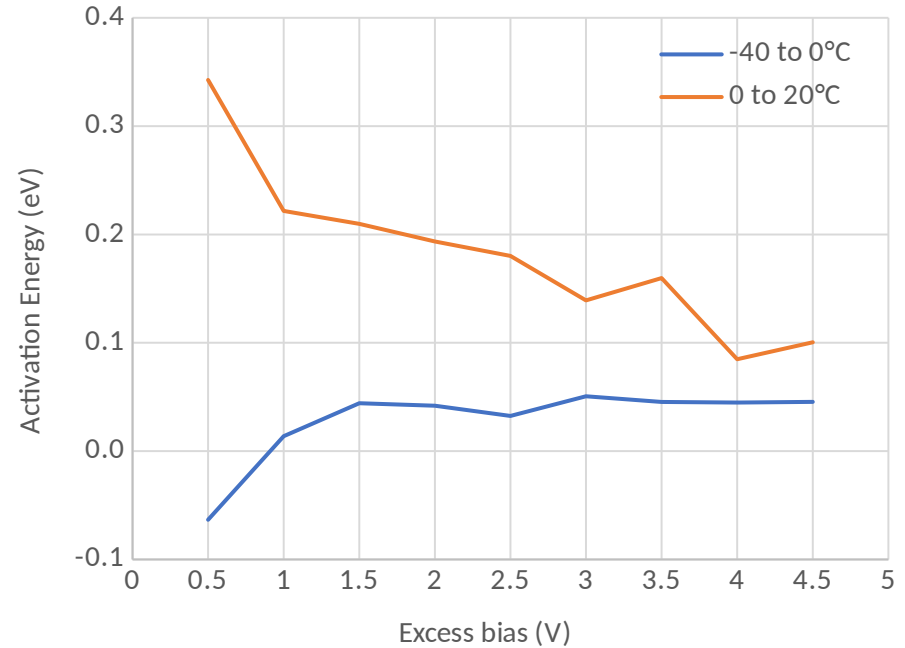
- Temperature range -40°C – 0°C
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- Activation energies ~ 0.2 eV \rightarrow DCR dominated by trap-assisted tunneling (Poole-Frenkel)



High dark-count rate prevents operation at higher overvoltages (cf. early SiPMs)

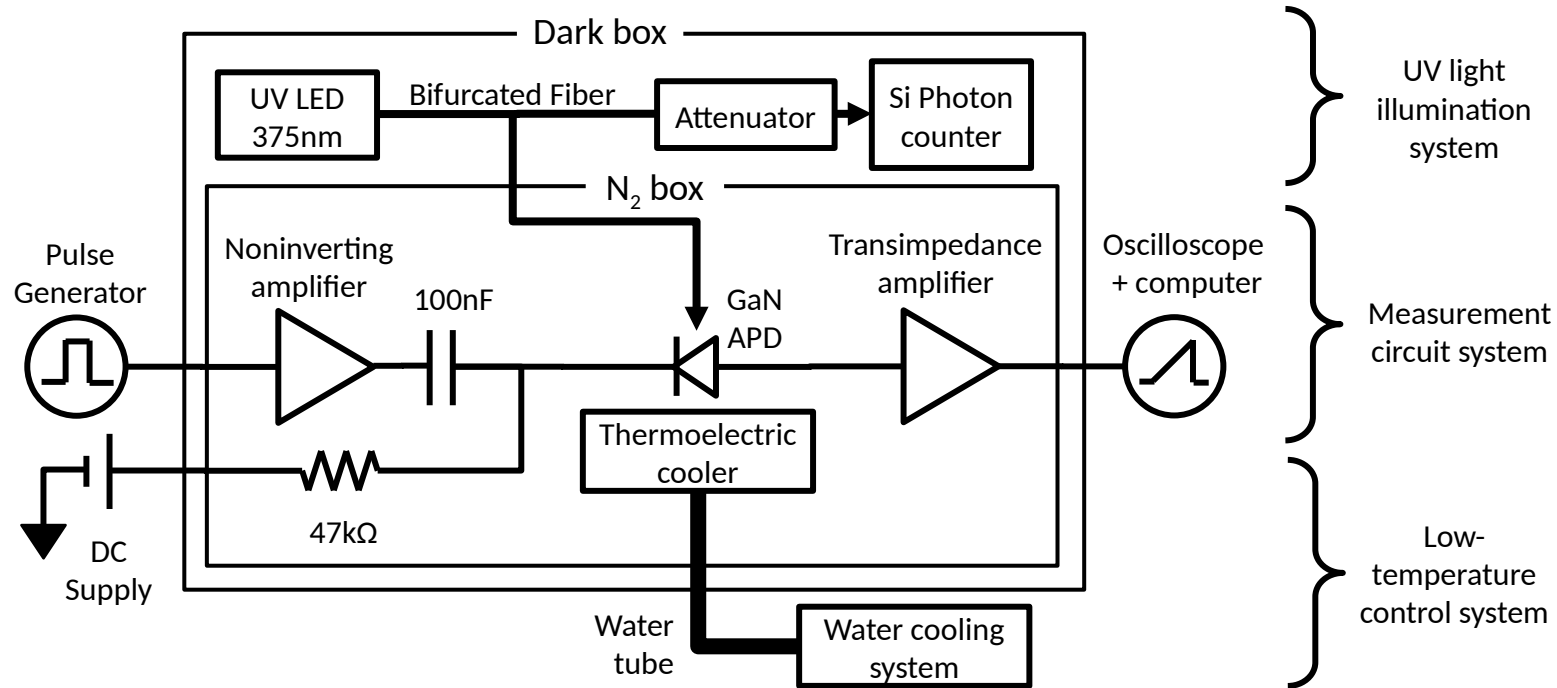
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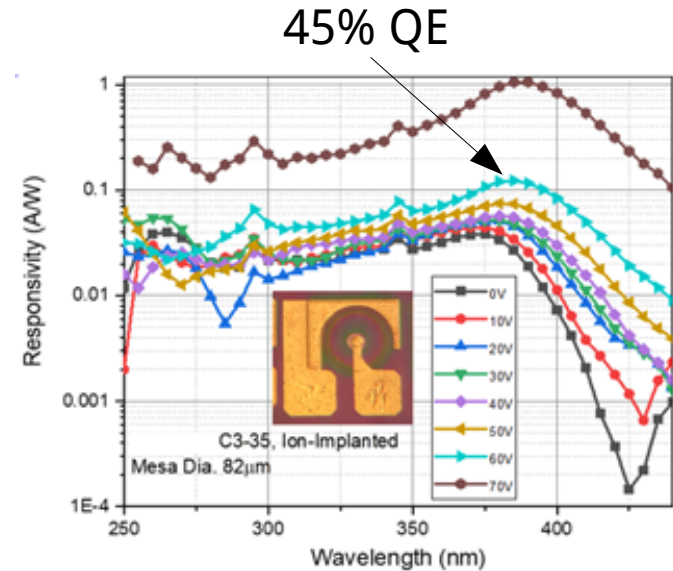
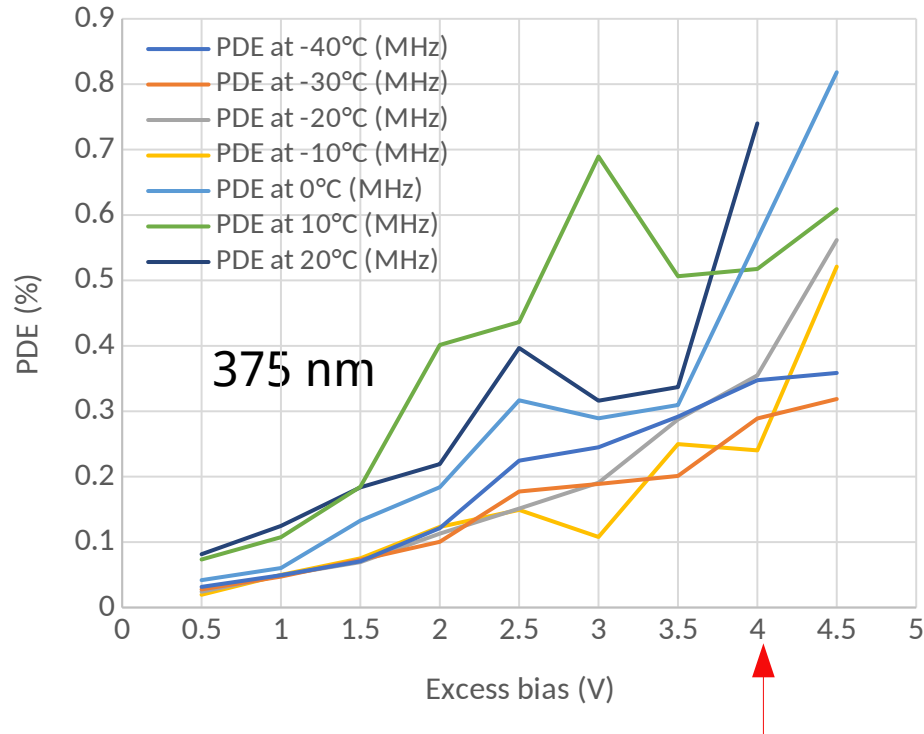


High dark-count rate prevents operation at higher overvoltages (cf. early SiPMs)

Photon Detection Efficiency: Setup



Photon Detection Efficiency

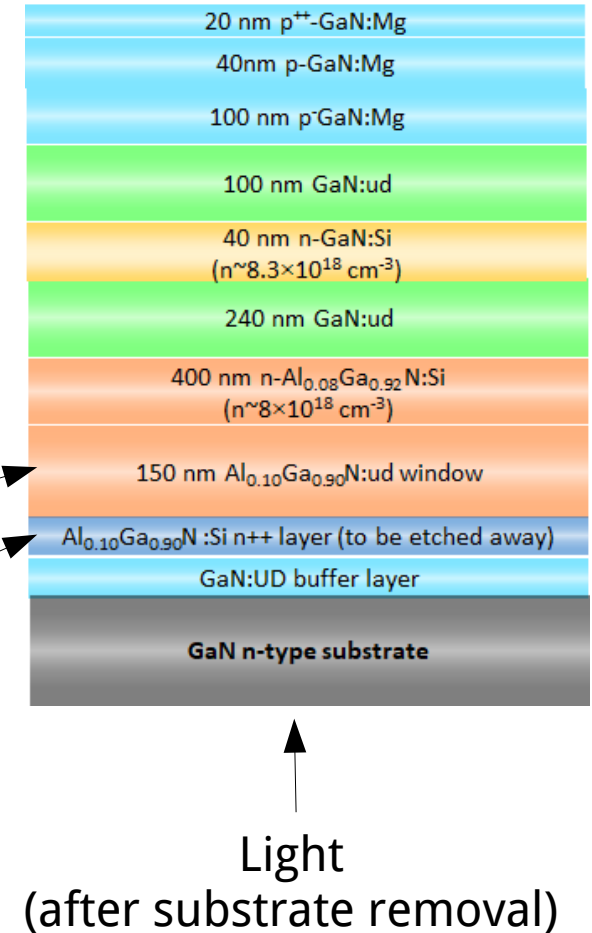


~1% breakdown probability at 4V overvoltage (~5% above breakdown voltage)

Operation at higher overvoltages will result in higher breakdown probabilities

Next Steps

- Reduce DCR -> Eliminate Poole-Frenkel tunneling
 - Impurity states in “intrinsic layer”
 - Residual crystalline defects
 - Growth studies have shown we can reduce “unintentional impurities” in the avalanche region
 - Employ low-defect III-N substrates
 - Further studies of ion-implantation
- AlGaN “window” for better UV sensitivity
- Back-side illumination designs
- Selective etching for substrate removal
- Provides for “flip-chip” mounting to Si bias/readout circuit



Summary

- GaN G-APDs have the potential for high (V)UV sensitivity.
- We succeeded in operating GaN diodes in Geiger mode.
 - All things considered the results are very encouraging.
- High DCR prevents operation at high breakdown probability.
 - Device can only operate <5% above breakdown -> latest SiPMs operate 10%-20% above breakdown -> lots of room for improvement.
 - Identified trap assisted tunneling as dominant DCR mechanism.
- The situation is very similar to early silicon SPADs and SiPMs.
 - No fundamental limitations identified.
 - The same methodology that improved SiPM characteristics can also improve GaN.

Look forward to our next generation of GaN SPADs.